

Silicon identification

This errata sheet applies to the M24128-BF and M24128-DF, which are 128 Kbit serial I²C bus EEPROMs, and specifically to the devices delivered in 8-bump wafer-level chip-scale packages (WLCSP).

[Table 1](#) shows the list of part numbers.

Table 1. Device summary

Reference	Part Number
M24128-BF	M24128-BFCS6TP/A
M24128-DF	M24128-DFCS6TP/K

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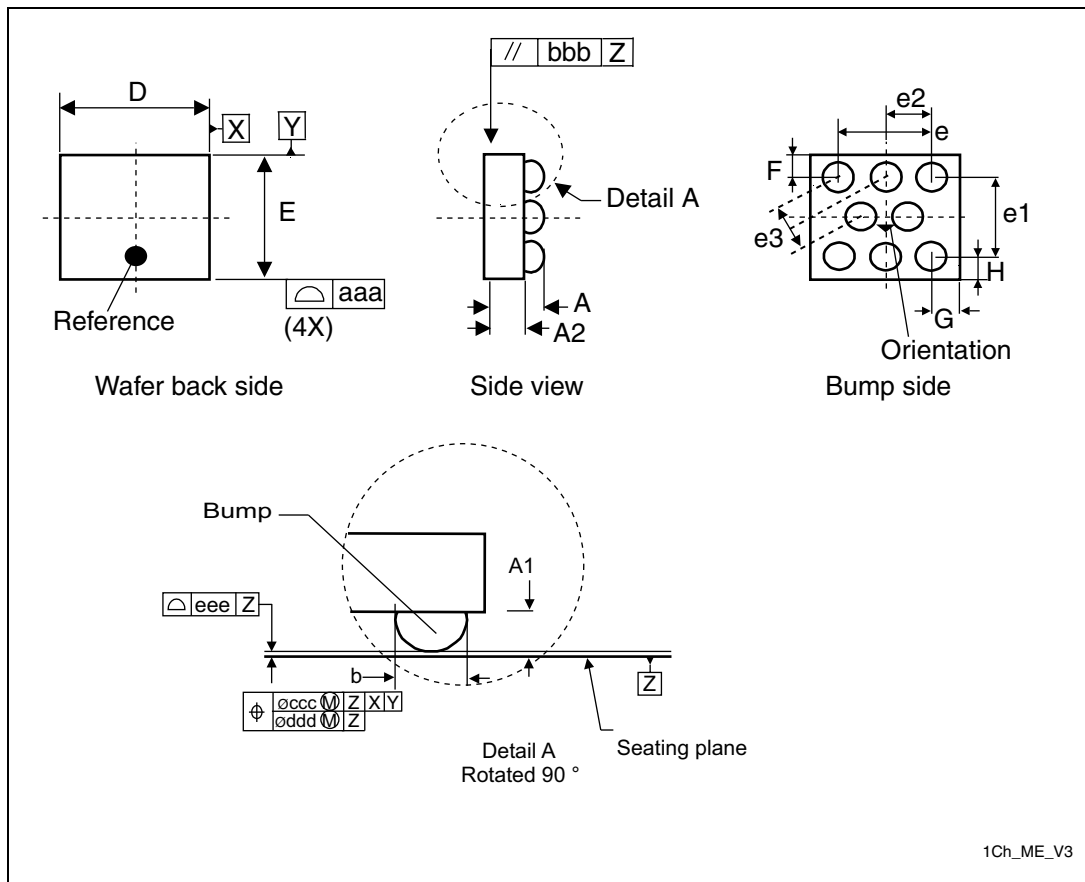
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1 M24128-BF and M24128-DF physical product change

There is not any physical product change.

Figure 1 shows the package outline.

Figure 1. WLCSP 8-bump, without BSC, 1.289 x 1.099 mm, wafer level chip scale package outline



The figures below show the difference between D and E dimensions in the front side view (see *Figure 2*), back side view (see *Figure 3*) and side view (see *Figure 4*).

Figure 2. D and E front side view

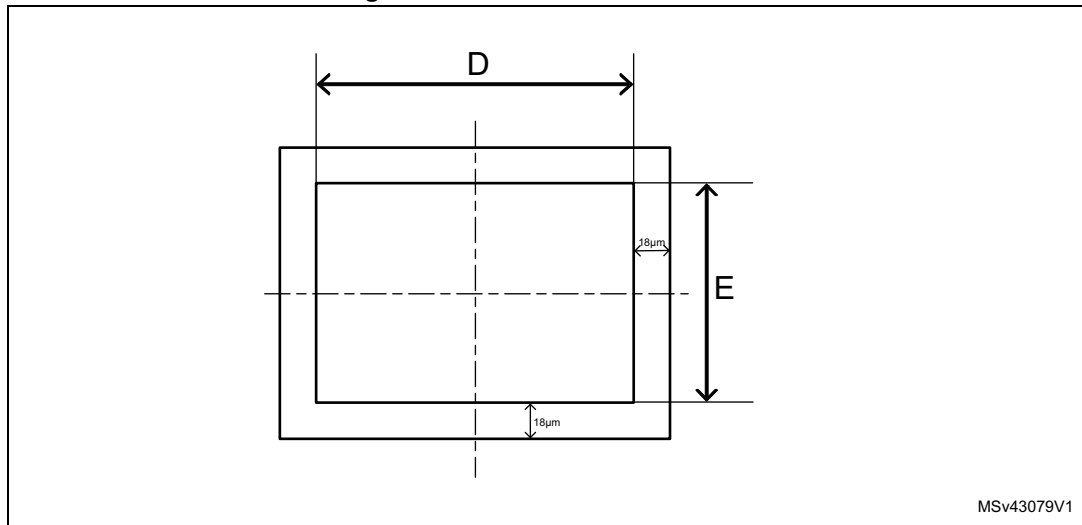


Figure 3. D and E back side view

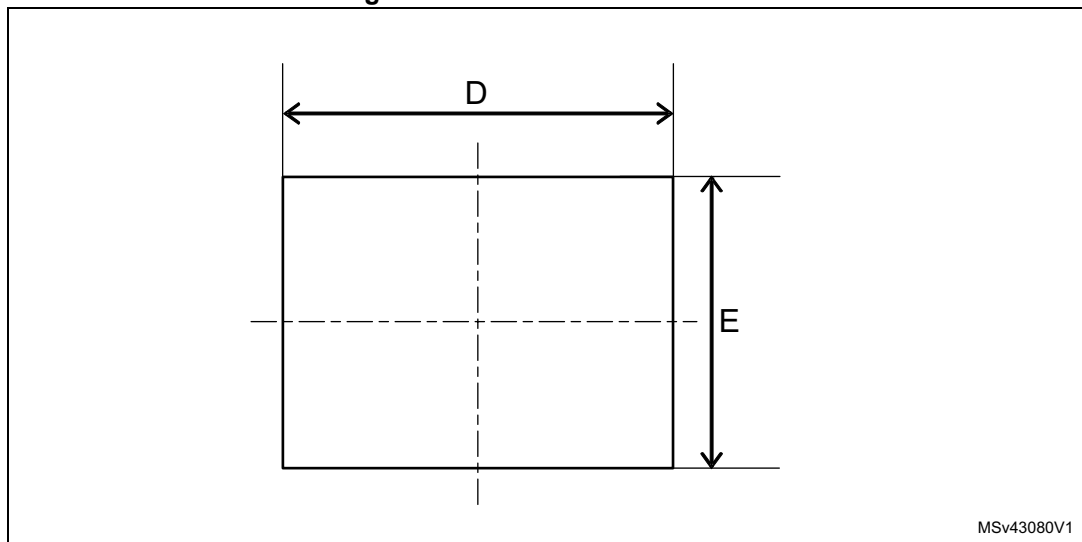
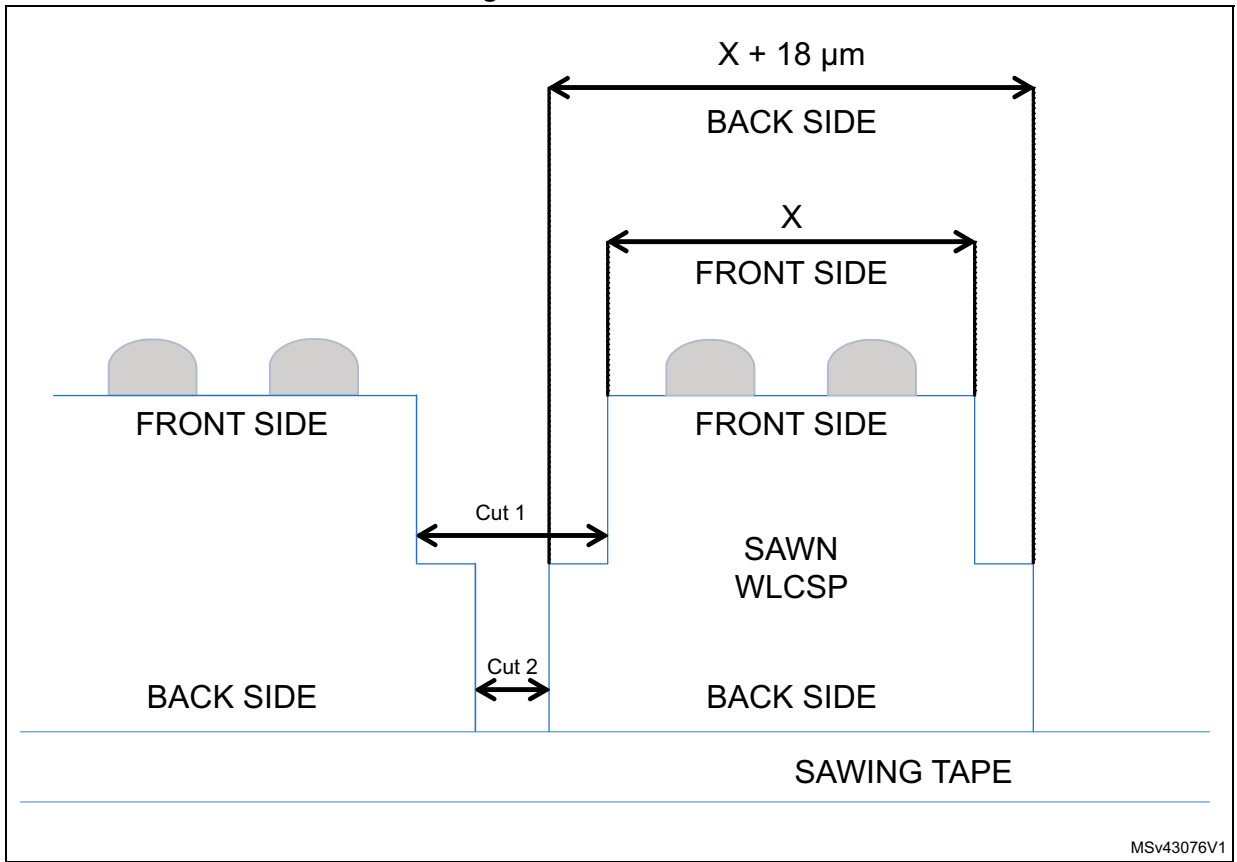


Figure 4. D or E side view



2 Package mechanical data modifications

This document refers to the changes in dimensions D and E (see [Figure 3](#)) described in the M24128-BF/M24128-DF datasheet, in tables detailing the dimensions of the WLCSP 8-bump package.

D and E values must be modified to correct the following mistake:

- The D and E values in the M24128-BF/M24128-DF datasheet correspond to front side view (ball side), instead of back side view (marking side view).
[Table 2](#) and [Table 3](#) report the data for the front and back view, respectively.

Table 2. D and E values corresponding to front side view

Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
D	-	1.271	1.291	-	0.0500	0.0508
E	-	1.081	1.101	-	0.0425	0.0433

Table 3. D and E values corresponding to back side view

Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
D	-	1.289	1.309	-	0.0507	0.0515
E	-	1.099	1.119	-	0.0433	0.0441

The difference between back side and front side dimension is 18 µm (0.018 mm). This difference is due to the two-step sawing process, where cut 1 and cut 2 are performed with blades having different thicknesses (see [Figure 4](#) in which X represents D or E and it has the same value and tolerance).

3 Revision history

Table 4. Document revision history

Date	Revision	Changes
15-Jul-2016	1	Initial release.

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